

$I_V = 3000$ mcd, $V_F = 3.3$ V
Through-hole LED
SELG2WA10C-S



Data Sheet

Description

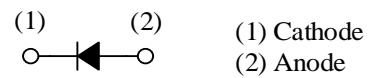
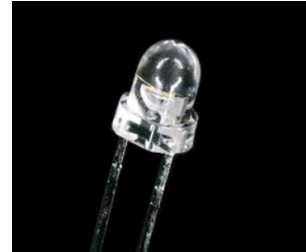
The SELG2WA10C-S is a through-hole white LED.

Package

φ3 mm Round

Features

- Color ----- White
- Lens Color ----- Clear
- Luminous Intensity, I_V -- 3000 mcd (typ.) ($I_F = 20$ mA)
- Forward Voltage, V_F ----- 3.3 V (typ.) ($I_F = 20$ mA)
- Chromaticity (x, y)----- (0.310, 0.320)
- Viewing Angle, $2\theta_{1/2}$ ----- 40 deg
- RoHS Compliant
- Pb-free, Soldering
- High Reliability



Not to scale

Applications

- Switch
- Indicator
- Illumination

SELG2WA10C-S

Absolute Maximum Ratings

Unless specifically noted, $T_A = 25\text{ }^\circ\text{C}$.

Parameter	Symbol	Conditions	Rating	Unit
Power Dissipation	P_D		114	mW
Forward Current	I_F		30	mA
Forward Current Reduction	ΔI_F	$T_A \geq 25\text{ }^\circ\text{C}$	-0.45	mA/ $^\circ\text{C}$
Pulse Forward Current	I_{FP}	Frequency = 1 kHz Pulse Width $\leq 100\text{ }\mu\text{s}$	100	mA
Reverse Voltage	V_R		3	V
Operating Temperature	T_{OP}		-30 to 85	$^\circ\text{C}$
Storage Temperature	T_{STG}		-30 to 100	$^\circ\text{C}$

Electrical / Optical Characteristics

Unless specifically noted, $T_A = 25\text{ }^\circ\text{C}$.

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 20\text{ mA}$	—	3.3	3.8	V
Reverse Current	I_R	$V_R = 3\text{ V}$	—	—	10	μA
Luminous Intensity	I_V	$I_F = 20\text{ mA}$	1185	3000	—	mcd
Chromaticity	x	$I_F = 20\text{ mA}$	—	0.310	—	—
	y		—	0.320	—	—
Viewing Angle	$2\theta_{1/2}$	$I_F = 20\text{ mA}$	—	40	—	deg

Luminous Intensity Bins

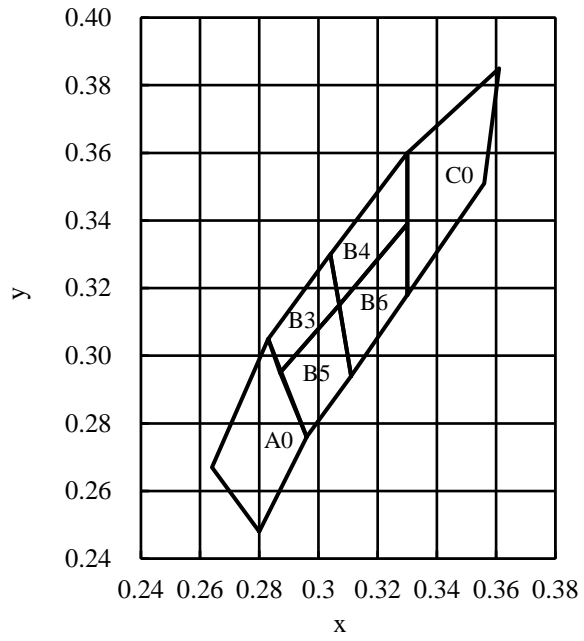
Bin Number	Luminous Intensity Range	Unit
F	1185 to 2370	mcd
G	1580 to 3160	mcd
H	2107 to 4214	mcd
I	2812 to 5623	mcd
J	3749 or more	mcd

SELG2WA10C-S

Chromaticity Bins

The values have a tolerance of $\pm 0.01\%$.

Bin Number	x	y
A0	0.2800	0.2480
	0.2960	0.2760
	0.2830	0.3050
	0.2640	0.2670
B3	0.2870	0.2950
	0.3070	0.3150
	0.3040	0.3300
	0.2830	0.3050
B4	0.3070	0.3150
	0.3300	0.3390
	0.3300	0.3600
	0.3040	0.3300
B5	0.2960	0.2760
	0.3110	0.2940
	0.3070	0.3150
	0.2870	0.2950
B6	0.3110	0.2940
	0.3300	0.3180
	0.3300	0.3390
	0.3070	0.3150
C0	0.3300	0.3180
	0.3560	0.3510
	0.3610	0.3850
	0.3300	0.3600



Derating Curves

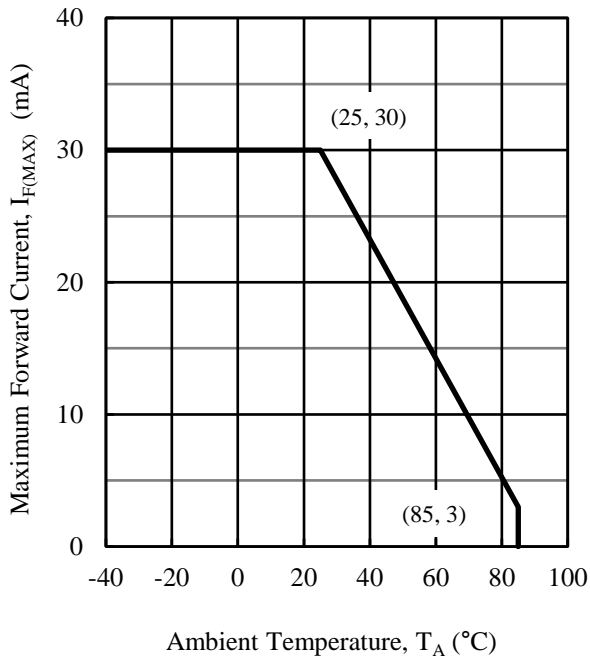


Figure 1. $I_{F(MAX)}$ vs. T_A

Characteristic Curves

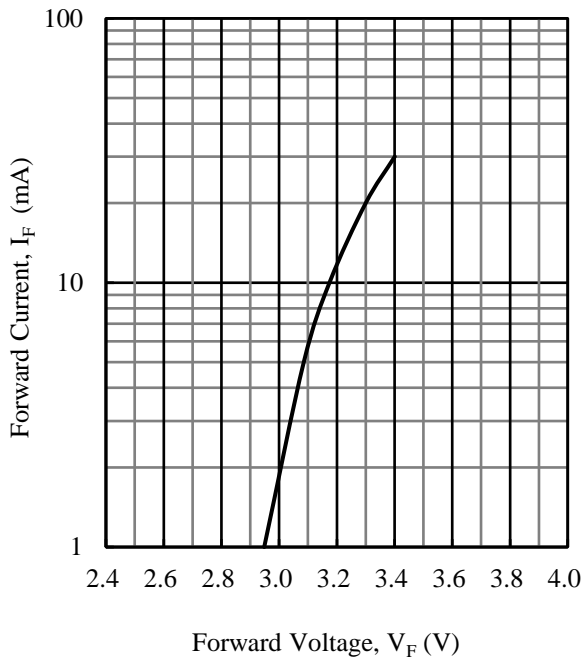


Figure 2. I_F vs. V_F

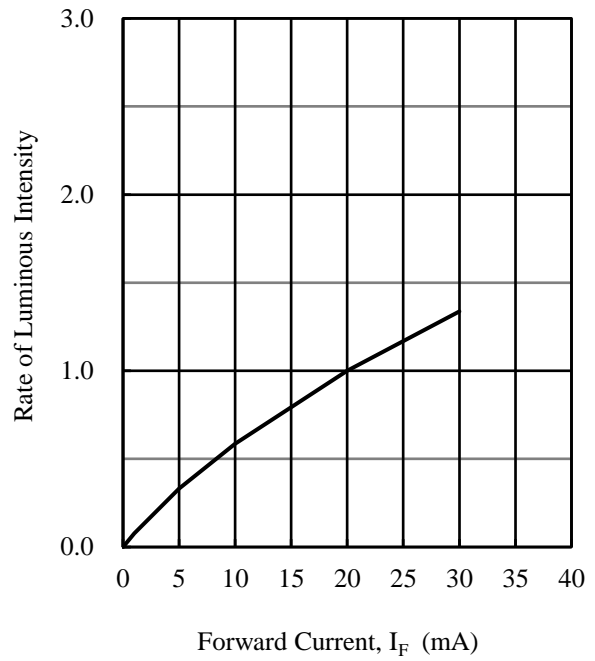


Figure 3. Rate of Luminous Intensity vs. I_F

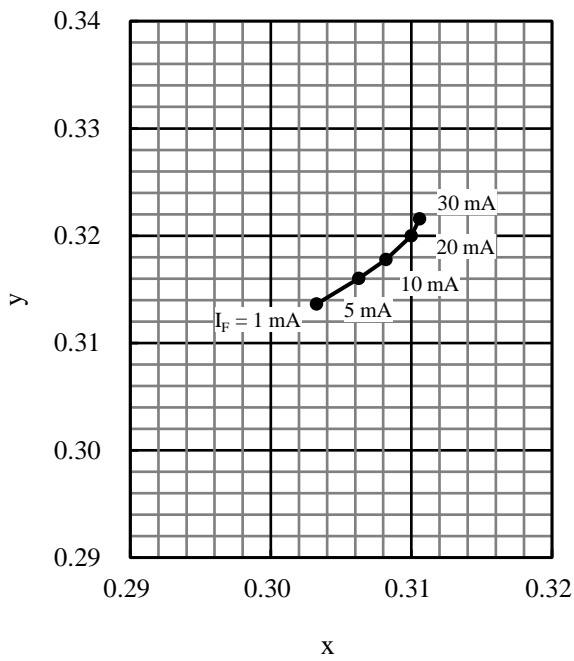


Figure 4. I_F vs. Chromaticity

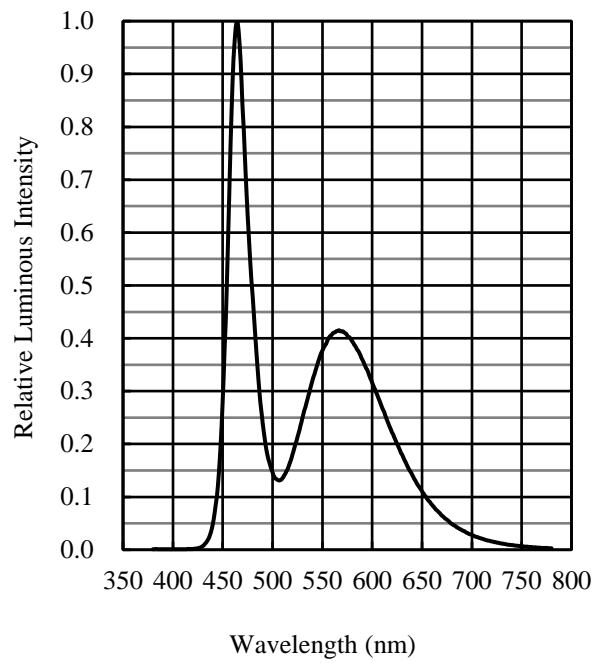


Figure 5. Spectrum

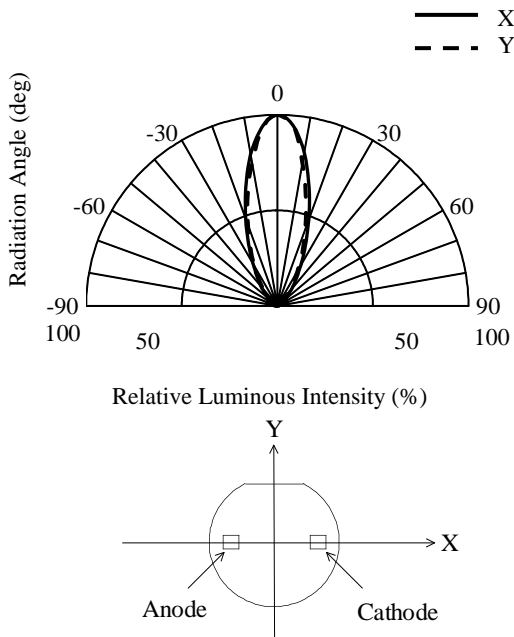
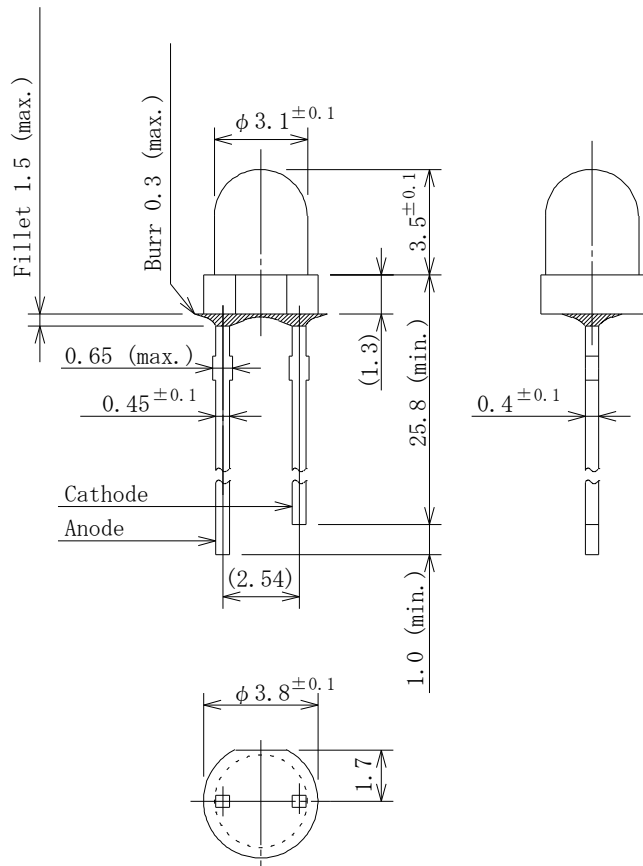


Figure 6. Directivity

SELG2WA10C-S

Physical Dimensions

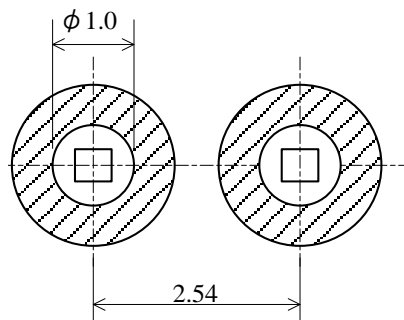
• Through-hole ($\phi 3$ mm Round)



NOTES:

- Dimensions in millimeters
- Unless specifically noted, tolerance is ± 0.3 .
- RoHS compliant

• Land Pattern Example



NOTES:

- Dimensions in millimeters
- All the dimensions without tolerance are for reference only.

Soldering Conditions

- When soldering the products, it is required to minimize the working time within the following limits:

- Flow:
 - Preheat: 90 °C / 120 s
 - Solder heating: 250 °C / 3 s
- Soldering iron: 350 ± 10 °C / 3 s, 1 time

Be sure to ensure a distance of ≥ 5.5 mm between the encapsulating resin and the solder.

- The following are the considerations in fixing the chip parts to be mounted on the same board as the product. When fixing such chip parts with an adhesive before soldering, extreme care should be taken not to heat the product before the adhesive is firmly cured (e.g., while it is being cured). Firstly, fix the chip parts other than the products with an adhesive. Secondly, heat to cure the adhesive before mounting the product. Finally, mount and solder the product. If there is no choice but to simultaneously heat the product and other chip parts for curing the adhesive, perform the simultaneous heating under the conditions listed below without any external force, stress, or excessive vibration applied to the product. After the adhesive is cured, cool the product to a room temperature and then perform soldering.
 - Solder heating temperature: ≤ 120 °C
 - Solder heating time: ≤ 60 s
- A hole pitch to be formed on a board should be identical to the pin pitch of the product.
- When mounting the product on a double-sided board, do not use plated through holes.

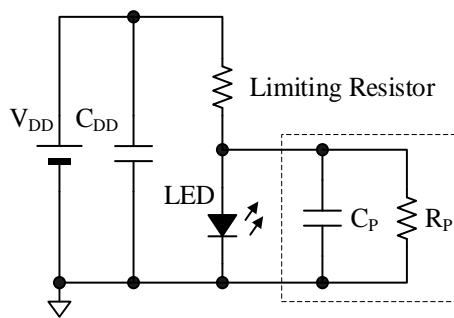
Precautions for Use

• Measures for Electrostatic Discharge (ESD)

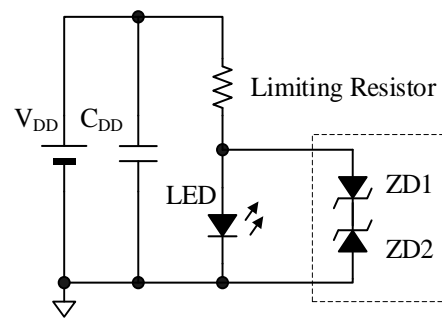
Because this product is sensitive to ESD, it is necessary to take adequate measures against ESD and surge for safe and proper handling. In particular, note that when a voltage that exceeds the absolute maximum rating is applied, the product may be damaged.

• Reference Protection Circuits for Electrostatic Discharge and Surge

The following figures show reference protection circuits that prevent the product from any damage due to ESD or surge. Note that these circuits are only examples; therefore, be sure to check the ESD and surge levels in your actual system and to take appropriate measures (e.g., adding a part) as needed.



Example of Adding Filter
($C_P \geq 0.01 \mu\text{F}$, $R_P = 10 \text{ k}\Omega$)



Example of Adding Zener Diodes
(ZD1, ZD2: $V_Z = 7 \text{ V}$ to 8 V)

• Other

- After soldering the product, care should be taken not to apply mechanical stress or excessive vibration until it cools to room temperature. A glass transition of the product's encapsulating resin will occur at temperatures from about 120 °C to 130 °C. When the resin temperature exceeds these temperatures, the resin softens rapidly. Therefore, applying stress or excessive vibration to the resin or pin at high temperatures may cause a shift in the pin alignment or a wire breakage.
- Do not cool the product rapidly.
- When mounting the product on a board, mounting position and orientation should be taken into account so that any stress due to board warpage is not applied to the product.
- Do not touch the encapsulating resin of the product with sharp objects such as a tweezer or fingernails. Also, do not use the product again after removal.
- Do not touch the product after mounting it on a board.
- The product emits a high-power light. Therefore, care should be taken not to look at the light emission directly for a long time because it may hurt your eyes.
- Use the product at rated current (sorting current) as much as possible. When the product is used at a current lower than the rated current (sorting current), a variation in forward voltage or luminous intensity may increase. Therefore, care should be taken for such variation when you use the product at low current.
- When using the product, care should be taken not to apply a voltage in the opposite direction of the LED.

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